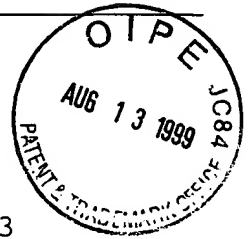


8/23-99

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

CHAD A. COBBLEY
TONGI JIANG
ED A. SCHROCK



Serial No. 08/916,629

Art Unit: 1733

Filing Date: AUGUST 22, 1997

Examiner: MITCHELL, S.

For: SEMICONDUCTOR DIE ATTACHMENT
METHOD AND APPARATUS

Attorney Docket No. 97-0098

**AMENDMENT
AUGUST 9, 1999**

Commissioner of Patents and Trademarks
BOX AMENDMENT (NON FEE)
Washington, D.C. 20231

Sir:

This is a response to the Office Action dated May 10, 1999 having a statutory period for response set to expire on August 10, 1999. Please amend the captioned case as follows.

In the Specification

On page 10, line 11, remove "a".

In the claims:

Please cancel claims 23-39.

a' 1. (amended) A method for attaching a semiconductor die to a leadframe:

providing a cyanoacrylate adhesive material formulated to cure in less than about 60 seconds at a temperature of about 20°C to 30°C and at an ambient atmosphere;

[dispensing an] applying the adhesive material [on] to the leadframe or to the die;